

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Canceled)
2. (Currently Amended) A cooling device for cooling a plurality of heat sources, comprising:
  - (1) a heat sink including a coolant, said heat sink comprising:
    - (a) a first heat sink member with a plurality of heat sources arranged at an outer surface of said heat sink; and
    - (b) a second heat sink member provided with a plurality of holes, said coolant that cools said plurality of heat sources ~~source~~ being made to pass through said holes;
  - (2) a header configured to an opposite side to said first heat sink member about said second heat sink member as an axis;
  - (3) an inlet port whereby said coolant is made to flow into a first space surrounded by said header and said second heat sink member; and
  - (4) an outlet port whereby said coolant in a second space surrounded by said first heat sink member and second heat sink member is made to flow out.
3. (Withdrawn) The cooling device for a heat source according to claim 2, wherein an upright plate is provided on a downstream side of said header.
4. (Withdrawn) The cooling device for a heat source according to claim 2, wherein an upright plate provided on a downstream side of said header is made of arcuate shape such as to surround a hole.

5. (Withdrawn) The cooling device for a heat source according to claim 2,  
wherein an upright plate provided on a downstream side of said header is provided offset from a center of a hole.
6. (Withdrawn) The cooling device for a heat source according to claim 2,  
wherein a gap between an upright plate provided on a downstream side of said header and a wall face on a side of said header opposite said holes is eliminated.
7. (Withdrawn) The cooling device for a heat source according to claim 2,  
wherein a baffle plate is provided on an upstream side of said holes within said heat sink.
8. (Withdrawn) The cooling device for a heat source according to claim 6,  
wherein a baffle plate provided on an upstream side of said holes within said heat sink is made of an arcuate shape such as to surround a hole.
9. (Withdrawn) The cooling device for a heat source according to claim 6,  
wherein a gap between a baffle plate provided on an upstream side of said holes within said heat sink and said wall face on a side of said heat sink opposite said holes is eliminated.
10. (Withdrawn) The cooling device for a heat source according to claim 2,  
wherein an upright plate on a downstream side of holes of said header and a baffle plate on an upstream side of said holes within said heat sink are provided.
11. (Withdrawn) The cooling device for a heat source according to claim 9,  
wherein said upright plate and said baffle plate respectively are made of an arcuate shape such as to surround a hole.
12. (Withdrawn) The cooling device for a heat source according to claim 2,

wherein a porous fluid resistance is arranged between an upstream end of said header and said holes.

13. (Withdrawn) The cooling device for a heat source according to claim 2,

wherein a porous fluid resistance is arranged on an upstream side of said holes.

14. (Withdrawn) The cooling device for a heat source according to claim 2,

wherein a plurality of headers are arranged on a side of holes arranged in said heat sink opposite that of said heat source.

15. (Withdrawn) The cooling device for a heat source according to claim 13,

wherein a flow path is provided whereby said coolant flowing out from said holes is returned to another header from within said heat sink.

16. (Withdrawn) The cooling device for a heat source according to claim 2, wherein said cooling device is constructed divided into a part where said heat source is arranged, a part where said holes are arranged and a header part.

17. (Withdrawn) A cooling device for a heat source comprising:

a header wherein one or a plurality of holes are respectively provided in wall faces on both sides;

a heat sink outside wall where a heat source is arranged on an outer surface with gaps being provided on both sides of said header;

an inlet port whereby coolant flows into said header; and

an outlet port whereby said coolant within said heat sink flows out.

18. (Previously Presented) A cooling device according to claim 2, wherein the plurality of holes comprises a first hole, a second hole and a third hole arranged in sequence

along a line without intervening holes and wherein the distance between the first hole and the second hole is different than the distance between the second hole and the third hole.

19. (New) A cooling device according to claim 2, wherein the plurality of heat sources comprise a plurality of semiconductor elements.